OKI

MSM9552/9553 IC for FM Multiplex Broadcast Reception User's Manual

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Chapter 1

GENERAL DESCRIPTION

1. GENERAL DESCRIPTION

The MSM9552 and MSM9553 are LSI devices which demodulate FM character multiplex signals in the DARC (DAta Radio Channel) format to acquire digital data. These devices operate on 5 V and 3 V, respectively. In the DARC format, baseband signals at ordinary FM broadcasting frequencies are multiplexed with 16 kbps digital data which are L-MSK-modulated at 76 kHz.

Each device has a bandpass filter consisting of SCF, frame synchronization circuit, and error correction circuit, on a single chip.

They allow a system for acquisition of digital data to be easily constructed by externally mounting an FM receiver tuner, microcontroller for control, and memory for temporary storage of data.

The MSM9552 and MSM9553 have a simple configuration, and are equipped with only necessary functions. By making changes to software for the external microcontroller, the MSM9552 and MSM9553 meet the various requirements of FM multiplex broadcasting services to be offered in future.

These devices are best suited for radio sets and information devices using FM character multiplex broadcasting, which began in Japan in October 1994. The MSM9553 is especially suitable for portable units.

Features

- Built-in Bandpass Filter (SCF)
- Built-in Block Synchronization Circuit and Frame Synchronization Circuit
- Setting of Synchronization Protecting Stage number
- Regeneration of Data Clocks by Digital PLL
- 1T Delay Detection
- Built-in Error Correcting Circuit
- Built-in Layer 4 and Layer 2 CRC Processing Circuit
- International Frame Formats A (supporting a real time block), B, and C available
- Microcontroller Parallel Interface
- Clock Output for External Devices (64 kHz to 8.192 MHz selectable)
- Power Source: 5 V (MSM9552), 3 V (MSM9553)
- Package: 44-pin plastic QFP (QFP44-P-910-0.80-2K) (Product name: MSM9552GS-2K, MSM9553GS-2K)

Chapter 2

BLOCK DIAGRAM

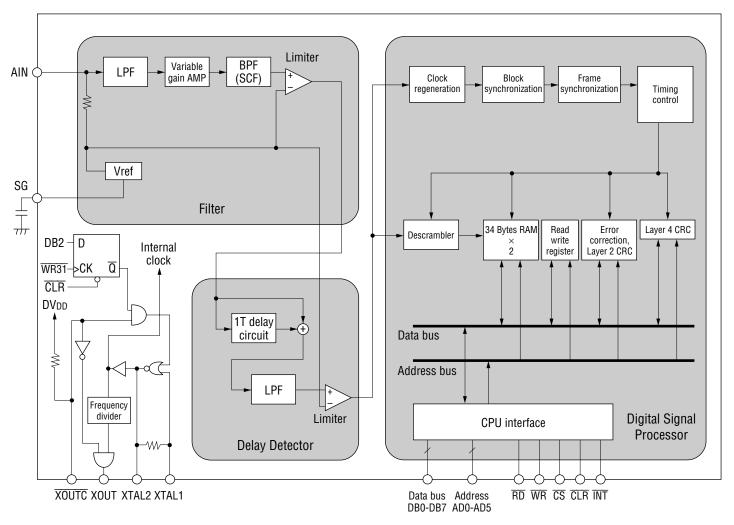


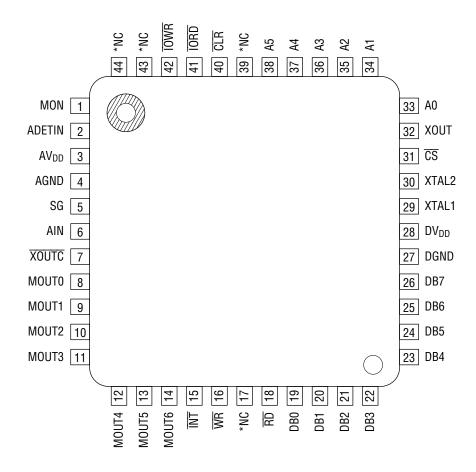
Figure 2.1 Block Diagram

Chapter 3

PIN INFORMATION

3. PIN INFORMATION

3.1 PIN CONFIGURATION (TOP VIEW)



44-Pin Plastic QFP

Figure 3.1 Pin Layout

^{*} Leave the NC pins (17, 39, 43, and 44) open.

3.2 PIN DESCRIPTIONS

Table 3.1 Pin Description

Function	Symbol	Pin	Туре	Description
Microcontroller	WR	16	I	Write signal to internal register.
interface	RD	18	I	Read signal to internal register.
	ĪNT	15	0	Interrupt signal to microcontroller. When set to
				"L", an interrupt is generated.
	CS	31	I	Chip select signal. When set to "L", the read, write,
				and data bus signals become effective.
	CLR	40	I	When set to "L", the internal register is initialized,
				and the IC enters power down mode.
	A0-A5	33-38	1	Address signal to internal register.
	DB0-DB7	19-26	1/0	Data bus signal to internal register.
Tuner interface	AIN	6	1	FM multiple signal input.
	SG	5	0	Analog reference voltage pin. Connect a
				capacitor between this pin and the analog ground
				pin to prevent noise.
Analog section	MON	1	0	Analog section waveform monitoring pin. The
test				mode setting for the blocks in the analog section
				is specified by the analog section control register.
	ADETIN	2	I	Analog signal input pin for testing.
Digital section	ĪŌRD	41,	I	Digital section test signal input pins (pulled up
test	TOWR	42		internally).
	MOUTO-	8-14	0	Digital section test signal and monitor output
	MOUT6			pins.
Clock	XTAL1	29	I	8.192 MHz crystal connection.
	XTAL2	30	0	8.192 MHz crystal connection.
	XOUT	32	0	Pin to supply variable clock (64 kHz to 8.192 MHz)
				to external devices.
	XOUTC	7	1	XOUT control. "L" sets XOUT output,
				"H" sets XOUT output inhibit. This pin is pulled up
				internally.
Power supply	AV_{DD}	3	_	Analog power supply.
	AGND	4	_	Analog ground.
	DV _{DD}	28	_	Digital power supply.
	DGND	27	_	Digital ground.

Chapter 4

ELECTRICAL CHARACTERISTICS

4. ELECTRICAL CHARACTERISTICS

4.1 MSM9552 ELECTRICAL CHARACTERISTICS

4.1.1 Absolute Maximum Ratings

No.	Parameter	Symbol	Condition	Rating	Unit	
4	Power supply voltage	AV_DD		-0.3 to +7.0		
ı		DV_DD	$AV_{DD} = DV_{DD}$	-0.3 (0 +7.0	V	
2	Input voltage	VI	Ta = 25°C	-0.3 to AV _{DD} + 0.3		
2	Output voltage	V ₀		-0.3 to DV _{DD} + 0.3		
3	Maximum power	D	Ta = 25°C, per package	400	mW	
3	dissipation	P_{D}	Ta = 25°C, per output	50	IIIVV	
4	Storage temperature	T _{STG}	_	−55 to +150	°C	

4.1.2 Recommended Operating Conditions

No.	Parameter	Symbol	Condition	Range	Unit	Applied Pin
-1	Power supply voltage	AV_{DD}	AV _{DD} = DV _{DD}	4.5 to 5.5	V	AV_{DD}
		DV_DD	AvDD = DvDD	4.5 10 5.5	V	DV_DD
2	Crystal oscillation	· ·		0 100 MUz . 100 nnm		XTAL1,
2	frequency	TXTAL	_	8.192 MHz ±100 ppm		XTAL2
0	FM multiplex signal	M	Composite signal in-	0 F to 0*	.,	AINI
3	input voltage	V _{AIN}	cluding multiplex signal	0.5 to 2*	V _{P-P}	AIN
4	Operating temperature	Ta	_	-40 to +85	°C	_

 $^{^*}$ The gain of the variable gain amplifier (VGain): \times 1, \times 1.5, \times 2, or \times 3. The VGain should be adjusted to satisfy the equation: V_{AIN} \times VGain = 1.5 V to 2.0 V.

4.1.3 DC Characteristics

 $(DV_{DD} = AV_{DD} = 5 \text{ V} \pm 10\%, DGND = AGND = 0 \text{ V}, Ta = -40 \text{ to } +85^{\circ}\text{C})$

No.	Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit	Applied Pin
	Input voltage	V _{IH}		0.8 × DV _{DD}	_	_		WR, RD, XOUTC, DB0 to DB7,
1		V _{IL}		_	_	0.2 × DV _{DD}	V	XTAL1, \overline{CS} , A0 to A5, \overline{CLR} , \overline{IORD} , \overline{IOWR}
2	Output voltage	V _{OH}	I _{OH} = −1 mA	DV _{DD} -0.5	_	_	V	MOUTO to MOUT6, INT,
	Output voltage	V _{OL}	I _{OL} = 2 mA	_	_	0.45		DB0 to DB7, XOUT
3	Input current 1	I _{IH1}	V _{IH} = DV _{DD}	_	_	2	- μΑ	WR, RD, CS, DB0 to DB7,
	input current 1	I _{IL1}	V _{IL} = DGND	-2	_	_		A0 to A5,
4	Input current 2	I _{IH2}	V _{IH} = AV _{DD}	_	_	2	пΛ	ADETIN
	mput current 2	I _{IL2}	V _{IL} = AGND	-2	_	_	μА	ADETIN
_ 5	Input current 3	I _{IH3}	$V_{IH} = DV_{DD}$	_	_	2	μΑ	XOUTC,
6	Pull-up current	I _{pull}	$DV_{DD} = 5 V,$ $V_{IL} = DGND$	8	35	110	μΑ	TORD, TOWR
7	Output off-leakage	I _{OH}	$V_{OH} = AV_{DD}$ During nonmonitoring (Hiz)	_	_	2	^	MON
	current	I _{OL}	$V_{OL} = AGND$ During nonmonitoring (Hiz)	-2	_	_	μΑ	IVIOIV
8	Supply current	laa	During operation, no load f = 8.192 MHz	_	16	32	mA	ΛV== DV==
		I _{DD}	During power down, no load	_	_	20	μА	AV _{DD} , DV _{DD}

4.1.4 AC Characteristics

No.	Parameter	Symbol*	Condition	Min.	Тур.	Max.	Unit	Applied Pin
		t _{SWR1}	_	10	_	_		WR, CS,
1	Write setup time						ns	A0 to A5,
		t _{SWR2}	_	60	_	_		DB0 to DB7
								$\overline{WR}, \overline{CS}$,
2	Write hold time	t _{HWR}	_	10	_	-	ns	A0 to A5,
								DB0 to DB7
3	Write pulse width	t _{WWR}	_	65	_	_	ns	WR
4	Read setup time	topp		10			ns	RD, CS,
	neau setup tiille	t _{SRD}	_	10			115	A0 to A5
5	Read hold time	tunn		10			ne	RD, CS,
	nead fiold time	t _{HRD}	_	10			ns	A0 to A5
6	Read pulse width	t _{WRD}	_	105	_	_	ns	RD
	Interval between error							
7	correction data write	t _{IWRWRE}	Error correction	250	_	_	ns	WR
	and write							
	Interval between error							
8	correction data read	t _{IRDRDE}	Error correction	250	_	_	ns	RD
	and read							
	Interval between error							\overline{WR} ,
9	correction data write	t _{IWRRDE}	Error correction	100	_	_	ns	$\frac{\overline{RD}}{\overline{RD}}$
	and read							
10	Interval between layer	t _{ICLRWR4}	Layer 4 CRC	100			ns	WR
	4 data clear and write	UCLRWR4	Layer 4 Ono	100			110	VVII
11	Interval between layer	t _{IWRWR4}	Layer 4 CRC	4.5			μS	WR
	4 data write and write	UVKVVK4	Layer 4 Ono	7.0			μο	VVII
12	Interval between layer	t _{IWRRD4}	Layer 4 CRC	4.5			μS	WR,
	4 data write and read	TWRRD4	Layer 4 Ono	т.0			μο	RD
13	Read data output	t _{DRD1}		_	_	95	ns	RD,
	delay (1)	וטאטי					110	DB0 to DB7
14	Read data output	t _{DRD2}	_	_	_	80	ns	RD,
	delay (2)	לטאטצ					110	DB0 to DB7
15	Interrupt CLR delay	t _{DINTCLR}	Step out interrupt	250			ns	ĪNT,
	Thiorrupt OLIT dolay	UNICLK	Error correction interrupt	200			110	WR
16	Error correction time	t _{ERRL}		_		274	μS	ĪNT,
	(Horizontal direction)	LEKKL				2/4	μο	DB0
17	Error correction time	rror correction time				_ 2178	116	ĪNT,
	(Vertical direction)	t _{ERRV}				2170	μ\$	DB0
_18	CLR pulse width	t _{WCLR}	_	200	_	_	ns	CLR

^{*} See section 4.3, "TIMING DIAGRAM".

4.1.5 Filter Characteristics

No.	Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit	Applied Pin
1	BPF pass band attenuation	GAIN1	72 to 80 kHz Variable gain amplifier gain: 0 dB	_		3.0	dB	MON
2	BPF block band attenuation (1)	GAIN2	0 to 53 kHz Variable gain amplifier gain: 0 dB	50	_	_	dB	MON
3	BPF block band attenuation (2)	GAIN3	100 to 500 kHz Variable gain amplifier gain: 0 dB	50	_	_	dB	MON

4.2 MSM9553 ELECTRICAL CHARACTERISTICS

4.2.1 Absolute Maximum Ratings

No.	Parameter	Symbol	Condition	Rating	Unit
4	Dower ounnly voltage	AV _{DD}		-0.3 to +7.0	
1	Power supply voltage	DV_DD	$AV_{DD} = DV_{DD}$	-0.3 (0 +7.0	V
	Input voltage	VI	Ta = 25°C	-0.3 to AV _{DD} + 0.3	
2	Output voltage	V ₀		-0.3 to DV _{DD} + 0.3	
	Maximum power	Б	Ta = 25°C, per package	400	\^/
3	dissipation	P_{D}	Ta = 25°C, per output	50	mW
4	Storage temperature	T _{STG}	_	−55 to +150	°C

4.2.2 Recommended Operating Conditions

No.	Parameter	Symbol	Condition	Range	Unit	Applied Pin
4	Power supply voltage	AV_DD	AV DV	0.7 to 2.2	V	AV_{DD}
		DV_DD	$AV_{DD} = DV_{DD}$	2.7 to 3.3		DV_DD
2	Crystal oscillation	f		8.192 MHz ±100 ppm	_	XTAL1,
2	frequency	f _{XTAL}	_	0.192 WITZ ±100 PPIII		XTAL2
3	FM multiplex signal	M	Composite signal in-	0.0 +0.0 0*	V _{P-P}	AIN
3	input voltage	V_{AIN}	cluding multiplex signal	0.2 to 0.9*		AIN
4	Operating temperature	Ta	_	-20 to +75	°C	_

 $^{^*}$ The gain of the variable gain amplifier (VGain): \times 1, \times 1.5, \times 2, or \times 3. The VGain should be adjusted to satisfy the equation: VAIN \times VGain = 0.6 V to 0.9 V.

4.2.3 DC Characteristics

(DV_{DD} = AV_{DD} = 3 V $\pm 10\%$, DGND = AGND = 0 V, Ta = -20 to +75°C)

No.	Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit	Applied Pin
1	Input voltage	V _{IH}		0.8 × DV _{DD}	_	_	٧	WR, RD, XOUTC, DB0 to DB7,
ı	Input voltage	V _{IL}			_	0.2 × DV _{DD}	V	XTAL1, \overline{CS} , A0 to A5, \overline{CLR} , \overline{IORD} , \overline{IOWR}
2	Output voltage	V _{OH}	I _{OH} = −1 mA	DV _{DD} -0.5	_	_	٧	MOUT0 to MOUT6, INT,
۷	Output voitage	V _{OL}	I _{OL} = 2 mA	_	_	0.45	•	DB0 to DB7, XOUT
3	Input ourrent 1	I _{IH1}	V _{IH} = DV _{DD}	_	_	2	^	WR, RD, CS, DB0 to DB7,
3	Input current 1	I _{IL1}	V _{IL} = DGND	-2	_	_	μА	A0 to A5,
4		I _{IH2}	V _{IH} = AV _{DD}	_	_	2		ADETIN
4	Input current 2	I _{IL2}	V _{IL} = AGND	-2	_	_	μΑ	ADETIN
5	Input current 3	I _{IH3}	$V_{IH} = DV_{DD}$	_	_	2	μΑ	XOUTC,
6	Pull-up current	I _{pull}	DV _{DD} = 3 V, V _{IL} = DGND	3	13	50	μΑ	TORD, TOWR
7	Output off-leakage	I _{OH}	$V_{OH} = AV_{DD}$ During nonmonitoring (Hiz)	_	_	2		MON
	current	I _{OL}	V _{OL} = AGND During nonmonitoring (Hiz)	-2	_	_	μΑ	IVIOIN
8	Supply current		During operation, no load f = 8.192 MHz	_	13	22	mA	۸۱/ ۱۵۱/
· O		I _{DD}	During power down, no load	_	_	10	μΑ	AV _{DD} , DV _{DD}

4.2.4 AC Characteristics

No.	Parameter	Symbol*	Condition	Min.	Тур.	Max.	Unit	Applied Pin
		tswr1	_	10	_	_		WR, CS,
1 V	Write setup time			400			ns	A0 to A5,
		t _{SWR2}	_	120	_	_		DB0 to DB7
	NA/vika hadd timaa							$\overline{WR}, \overline{CS}$,
2 V	Write hold time	t _{HWR}	_	10	_	_	ns	A0 to A5,
- 1	Marita mulaa middh			100				DB0 to DB7
3 V	Write pulse width	t _{WWR}	_	130	_	_	ns	RD, CS,
4 F	Read setup time	t _{SRD}	_	10	_	_	ns	A0 to A5
5 F	Read hold time	+		10			ne	RD, CS,
3 1	neau iioiu iiiile	t _{HRD}	_	10			ns	A0 to A5
6 F	Read pulse width	t _{WRD}	_	160	_	_	ns	RD
	Interval between error							
	correction data write	t _{IWRWRE}	Error correction	250	_	_	ns	WR
	and write							
	Interval between error correction data read	+	Francisco	250			no	RD
	and read	t _{IRDRDE}	Error correction	250			ns	טח
	Interval between error							
		t _{IWRRDE}	Error correction	100	_	_	ns	\overline{WR} ,
	and read		- IWANDE ETTOT GOTTOGROTI				110	RD
	Interval between layer							
10	4 data clear and write	t _{ICLRWR4}	Layer 4 CRC	100	_	_	ns	WR
11	Interval between layer	+	Lauran A CDC	1 5				WR
4	4 data write and write	t _{IWRWR4}	Layer 4 CRC	4.5		_	μs	WH
12	Interval between layer	t _{IWRRD4}	Layer 4 CRC	4.5		_	μS	WR,
4	4 data write and read	4WKKD4	Layer 4 Orto	7.0			μο	RD
13	Read data output	t _{DRD1}	_	_	_	160	ns	RD,
	delay (1)							DB0 to DB7
14	Read data output	t _{DRD2}	_	_	_	160	ns	RD,
	delay (2)		Step out interrupt					DB0 to DB7
15 I	Interrupt CLR delay	t _{DINTCLR}	Error correction interrupt	250	_	_	ns	WR
	Error correction time		Lifor correction interrupt					INT,
16	(Horizontal direction)	t _{ERRL}	_	_	_	274	μs	DB0
F	Error correction time							INT,
17	(Vertical direction)	t _{ERRV}	_	_	_	2178	μs	DB0
	CLR pulse width	t _{WCLR}	_	200	_	_	ns	CLR

^{*} See section 4.3, "TIMING DIAGRAM".

4.2.5 Filter Characteristics

No.	Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit	Applied Pin
1	BPF pass band attenuation	GAIN1	72 to 80 kHz Variable gain amplifier gain: 0 dB	_	_	3.0	dB	MON
2	BPF block band attenuation (1)	GAIN2	0 to 53 kHz Variable gain amplifier gain: 0 dB	50	_	_	dB	MON
3	BPF block band attenuation (2)	GAIN3	100 to 500 kHz Variable gain amplifier gain: 0 dB	50	_	_	dB	MON

4.3 TIMING DIAGRAM

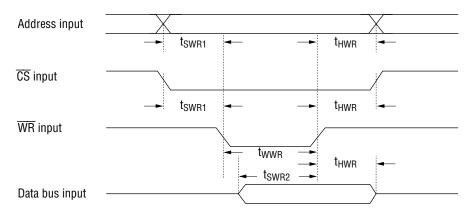


Figure 4.1 Write Timing

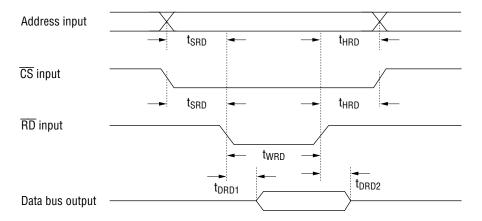


Figure 4.2 Read Timing

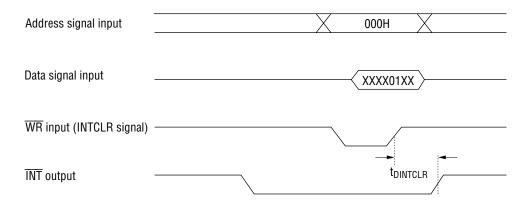


Figure 4.3 Interrupt CLR Timing

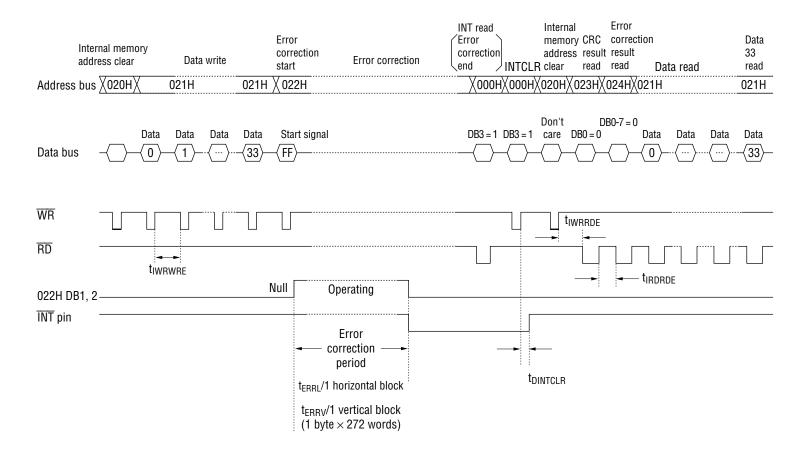


Figure 4.4 Error Correction Timing Diagram

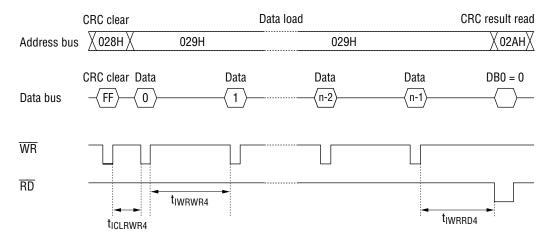


Figure 4.5 Layer 4 CRC Timing Diagram

Chapter 5

CONTROL REGISTERS

5. CONTROL REGISTERS

5.1 INTERRUPT REGISTERS

5.1.1 Interrupt source

These registers indicate the four types of interrupt factors: (1) receive interrupt, (2) 1st horizontal error correction completion, (3) out of sync., and (4) vertical error correction/2nd horizontal error correction completion. When an interrupt occurs, "1" is written. The registers must be externally cleared after reading, however clear conditions are different for each interrupt factor. For details see Table 5.1.1.

						<u>/</u> (4) —	<u>/</u> (3) <u> </u>	<u>/</u> (2) <u> </u>	<u>/ (1)</u>
Address		DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
	Reset value	_	_	_	_	0	0	0	0
000H	Read/write	_	_	_	_	Read/	Read/	Read/	Read/
	(Note)					write	write	write	write

(Note) Write is used to clear the interrupt.

Write = "1" : clear Write = "0" : none

Table 5.1.1 Interrupt Sources

Туре	Generation Condition	Generation Cycle	Clear Condition
INT0	At the time one block is	Every time 34 bytes are	1. Write DB0 = "1" to INT
Receive interrupt	received in a frame/block	received (18 ms).	(000H).
(000H, DB0)	synchronization state.		2. Clear the $\overline{\text{CLR}}$ pin.
	(Data is received only in a		(Initial setting)
	synchronized status; not		
	received in an out-of-sync. state.)		
INT1	At the time1st horizontal error	0.274 ms after 1st error	1. Write DB1 = "1" to INT
1st horizontal error	correction is completed.	correction start signal is	(000H).
correction completion		written.	2. Clear the CLR pin.
(000H, DB1)			(Initial setting)
INT2	When frame is out of	(070/4 /number of forward \+123) 10 mag	1. Write DB2 = "1" to INT
Out of synchronization	synchronization.	$(272/4 \times (number of forward) + 123) \times 18 ms$	(000H).
(000H, DB2)		This comes out at 10 to 12	2. Clear the CLR pin.
		seconds when the number of	(Initial setting)
		forward protection steps is 8.	
INT3	At the time error correction is	When the time shown in the	1. Write DB3 = "1" to INT
Vertical/horizontal	completed.	table below has elapsed after	(000H).
2nd error correction completion		an error correction start signal	2. Clear the CLR pin.
(000H, DB3)		is written (see table below).	(Initial setting)

	Error	Time	Data	
Havimantal	No*	0.138 ms	0.4 h. daa	
Horizontal	Yes 0.274 ms		34 bytes	
Mantinal	No*	1.090 ms	070 hudaa	
Vertical	Yes	2.178 ms	272 bytes	

^{*}Error correction is skipped when there is no error.

5.1.2 INT Mask

This register controls interrupt generation.

	nio rogiotor coi	11.010 1111011		/	(1) ———				
Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
001H	Write	value	_	_	_	_	0	0	0	0

(1) DB0-DB3:

0: INT0-INT3 interrupt disabled1: INT0-INT3 interrupt enabled

INT0: Receive interrupt

INT1: 1st horizontal error correction completion interrupt

INT2: Out-of-sync interrupt

INT3: Vertical/2nd horizontal error correction completion interrupt

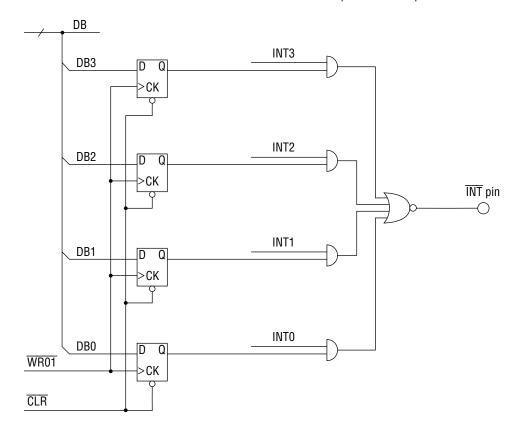


Figure 5.1.1 INT Mask Register

5.2 RECEIVE DATA REGISTERS

5.2.1 Receive Block Status

This register indicates the status of the received block data, which consists of the following: (1) Frame Number Change, (2) Frame Number, (3) Block Synchronization Status, (4) Parity Block Indication, (5) Frame Synchronization Status, (6) Layer 2 CRC Result, and (7) Real Time Block Indication

(7) \(\tau \) (6) \(\tau \) (5) \(\tau \) (3) \(\tau \) (2) \(\tau \)									<u>_</u> (1) <u>_</u>	
Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
002H	Read	value	0	0	0	0	0	0	0	0

(1) DB0: FNCHG (Frame Number Change)

0: No frame number changed

1: "1" is indicated when receive data is the first data (2nd byte) of block number 1, 14, 137, 150 for Method A, and block numbers 1, 61, 131, 191 for Method B.

(2) DB1-DB2: Frame Number

Indicates that the receive data is data of the following block number groups.

		R	eceive Data
DB2	DB1	Method B	Method A
0	0	Receive data of block numbers 1 to 13	Receive data of block numbers 1 to 60
0	1	Receive data of block numbers 14 to 136	Receive data of block numbers 61 to 130
1	0	Receive data of block numbers 137 to 149	Receive data of block numbers 131 to 190
1	1	Receive data of block numbers 150 to 272	Receive data of block numbers 191 to 272
			(Method A0)
			Receive data of block numbers 191 to 284
			(Method A1)

(3) DB3: Block Synchronization Status

0: Indicates receive data in a block out-of-sync state

1: Indicates receive data in a block sync state

(4) DB4: Parity Block Indication

This bit indication is available only in a frame synchronization state.

0: Receive data is not the data of the parity block.

1: Receive data is of the parity block.

- (5) DB5: Frame Synchronization Status Indication
- 0: Receive data is in a frame out of sync state.
- 1: Receive data is in a frame sync state.
- (6) DB6: CRC Result Indication
- 0: Indicates that the CRC result for the receive data is normal.
- 1: Indicates that the CRC result for the receive data is an error.
- (7) DB7: REAL Block Indication

This indication is used for receive block data in a frame sync state when frame A is set in the frame method register (01FH).

- 0: Receive data is not of the REAL block.
- 1: Receive data is of the REAL block.

5.2.2 Receive Data RAM Port

This port is used for one block receive data RAM of 34 bytes excluding BIC.

When an interrupt occurs, the internal memory addresses are cleared to zero.

Since the next receive data is output at the rising edge of an RD03 signal, 34 bytes can be read successively.

The status of receive data is shown in 5.2.1.

						(1	I) ———			
Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
003H	Read	value	Undefined							
			b7	b6	b5	b4	b3	b2	b1	b0

5.2.3 Receive RAM, Data Accumulation Condition, and Address Clear

- (1) DB1: This register specifies the condition (frame/block synchronization) for accumulating data into the receive RAM.
 If any data is written to this register, the receive RAM addresses are cleared to zero.
 Write the following data before reading the receive RAM second time and thereafter.
 - 0: Receive data is accumulated in receive RAM when the frame is synchronized.
 - 1: Receive data is accumulated in receive RAM when the block is synchronized. However, when frame synchronization is entered, receive data is accumulated even if the block is out of sync.

									<u>/</u> _(1) _	
Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
004H	Write	value	_	_	_	_	_	_	0	_

5.2.4 BIC Monitor

This register indicates the block indentification code (BIC) of the block receive data.

								<u>/</u> _(1) _	(2	′1——
Address	Read/Write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
007H	Read	value	_	_	_	_	_	0	0	0

- (1) DB2: When BIC is detected, "1" is indicated.
- (2) DB0 DB1: The detected BIC is output as shown below.

DB1	DB0	BIC number
0	0	BIC 1
0	1	BIC 2
1	0	BIC 3
1	1	BIC 4

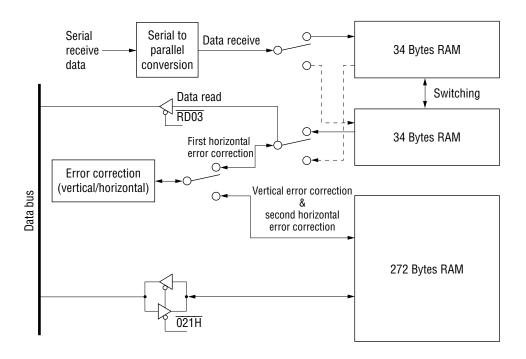


Figure 5.2.1 Receive RAM Configuration

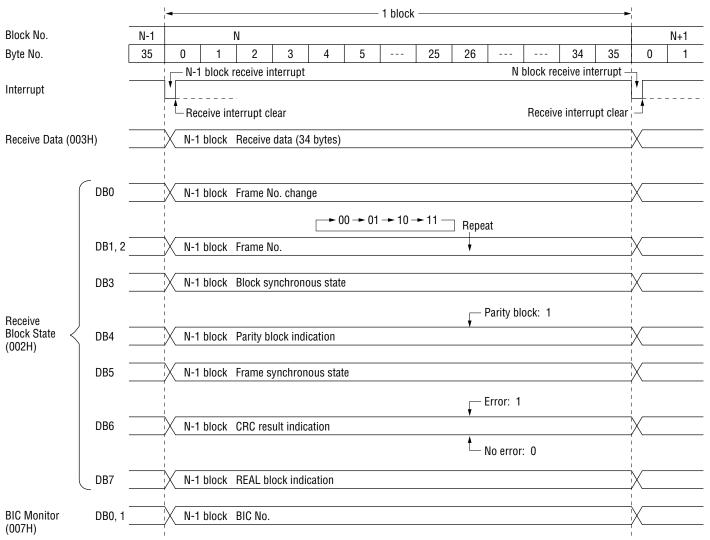


Figure 5.2.2 Receive Data Timing Diagram

5.3 CLOCK REGENERATION REGISTERS

5.3.1 Fixed Phase Adjustment

This register adjusts the phase of a 16 kHz data sampling clock in 1/125 steps within the range of -1/5 to +24/125. This register is used for initial settings.

			<u></u> (3) ¬	./	<u>(2) —</u>		/	<u>— (1) — </u>		
Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
H800	Write	value	_	0	0	0	0	0	0	0

(1) DB0-DB2: Phase delay settings in 1/125 steps

	1		
DB2	DB1	DB0	Phase Delay Setup Value
0	0	0	0/125
0	0	1	1/125
0	1	0	2/125
0	1	1	3/125
1	0	0	4/125
1	0	1	Inhibit
1	1	0	Inhibit
1	1	1	Inhibit

(2) DB3-DB5: Phase delay settings in 1/25 steps

DB5	DB4	DB3	Phase Delay Setup Value
0	0	0	0/25
0	0	1	1/25
0	1	0	2/25
0	1	1	3/25
1	0	0	4/25
1	0	1	Inhibit
1	1	0	Inhibit
1	1	1	Inhibit

(3) DB6: Phase advance setting in 1/5 steps

DB6	Phase Lead Setup Value
0	0
1	1/5

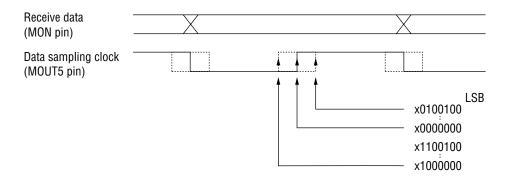


Figure 5.3.1 Phase Adjustment

5.3.2 Bit Gate

This register sets the gate width centered around the rising edge of the data clock. Gate width can be changed depending on parameters set before and after block synchronization. This function is for varying the constant of integration for the clock sampling timing detected inside and outside the gate. This register is used for initial settings.

							/ (4	2) —	/ (1) —
Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
009H	Write	value	_	_	_	_	0	0	0	0

(1) DB0-DB1: Before block synchronization

(2) DB2-DB3: After block synchronization

After Block Sy	nchronization	Before Block S	Synchronization		-1-			
DB3	DB3 DB2		DB1 DB0		Gate			
0	0	0	0	Gate 0				
0	1	0	1	Gate 1	±10%			
1	0	1	0	Gate 2	±20%			
1	1	1	1	Gate 3	±30%			

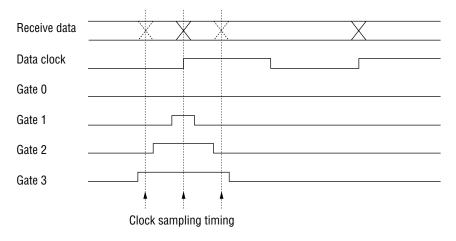


Figure 5.3.2 Clock Sampling Gate

5.3.3 Integration Constant

This register sets the timing sampling count required for phase control. The parameters are before and after block synchronization, and inside and outside the gate. This register is used for initial settings.

(1) Integration constant before block synchronization, outside the gate (0-15)

Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
00AH	Write	value	_	_	_	_	0	0	1	0

(2) Integration constant before block synchronization, inside the gate (0-15)

Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
00BH	Write	value	_	_	_	_	0	0	1	0

(3) Integration constant after block synchronization, outside the gate (0-63)

Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
00CH	Write	value	_	_	0	1	1	0	0	0

(4) Integration constant after block synchronization, inside the gate (0-63)

Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
00DH	Write	value	_	_	0	1	1	0	0	0

5.3.4 Phase Correction Step

This register sets the phase correction step width of DPLL used for data clock regeneration. This register can be used to adjust data clock supply speeds or data clock jitter control. Phase correction step widths can be changed depending on parameters set before or after block synchronization. This register is used for initial settings.

$(2) \longrightarrow (1) -$											
Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	
00EH	Write	value	_	_		_	0	1	0	1	
							b1	b0	b1	b0	

Time constants can be set as shown in Table 5.3.1 by combining the integration constants shown in Sections 5.3.3 and 5.3.4.

Table 5.3.1 Phase Correction Step

	_	Integratio	n Constant		After Block Synchronization										
b	b	Phase		Before Block Synchronization											
Ĩ	Õ	Correction S	Step	1	2		4		8		16		32		64
				4000	2000		1000		500		250		125		62.5
		1/ (= 0.4% = 4 4 MHz	4000 ppm)	ppm	ppm		ppm		ppm		ppm		ppm		ppm
0	0	Packet count required for a 1-bit phase displacement		0.69 Packet	1.38 Packet		2.77 Packet		5.55 Packet		11.1 Packet		22.2 Packet		44.4 Packet
		2/ (= 0.8% = 8 4 MHz			4000 ppm		2000 ppm		1000 ppm		500 ppm		250 ppm		125 ppm
0	1		Packet count required for a 1-bit phase displacement	0.34 Packet	0.69 Packet		1.38 Packet		2.77 Packet		5.55 Packet		11.1 Packet		22.2 Packet
1	0	4/ (= 1.6% = 16000 ppm) 4 MHz		16000 ppm	8000 ppm		4000 ppm		2000 ppm		1000 ppm		500 ppm		250 ppm
1	1		Packet count required for a 1-bit phase displacement	0.17 Packet	0.34 Packet		0.69 Packet		1.38 Packet		2.77 Packet		5.55 Packet		11.1 Packet

5.4 BLOCK SYNCHRONIZATION REGISTERS

5.4.1 Allowable Number of BIC Error Bits

This register specifies how many erroneous bits can be allowed in the block identification code (BIC). Values can be changed depending on parameter values before and after block synchronization. This register is used for initial settings.

							/ (ž	<u>2) — </u>	/(1) —
Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
010H	Write	value	_	_	_	_	0	1	1	0

(1) Allowable number of erroneous BIC bits before block synchronization

DB1	DB0	Allowable Number of Erroneous Bits in BIC Before Block Synchronization
0	0	0
0	1	1
1	0	2
1	1	3

(2) Allowable number of erroneous BIC bits after block synchronizaiton

DB3	DB2	Allowable Number of Erroneous Bits in BIC After Block Synchronization
0	0	0
0	1	1
1	0	2
1	1	3

5.4.2 Number of Block Synchronization Backward Protection Steps

This register specifies the number of block synchronization backward protection steps. When block identification codes (BICs) are successively detected for a specified number of times, the internal bit counter and the bit position of the block (0-287) are synchronized. This register is used for initial settings.

									/ (1) —
Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
011H	Write	value	_	_	_	_	_	_	0	1

(1) DB0-DB1: Number of block synchronization backward protection steps

DB1	DB0	Block proving in synchronization step count
0	0	Inhibit
0	1	2
1	0	3
1	1	4

5.4.3 Number of Block Synchronization Forward Protection Steps

This register specifies the number of block synchronization forward protection steps. If BICs cannot be detected successively for a specified number of times after block synchronization, the block is regarded as out of synchronization. This register is used for initial settings.

								(1) ——	
Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
012H	Write	value	_	_	_	_	1	0	0	0

(1) DB0-DB3: Number of block synchronization forward protection steps

DB3	DB2	DB1	DB0	Number of Block Synchronization Forward Protection Steps
0	0	0	0	0 (Inhibit)
0	0	0	1	1
	1	1	1	
1	1	1	1	15

5.4.4 Block Synchronization Monitor

- (1) Block synchronization monitoring register (DB0)
- (2) Registers to monitor the number of block synchronization forward protection steps (DB4-DB7). Both (1) and (2) are used for testing.

		<u>(1)</u>								
Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
013H	Read	value	0	0	0	0	_	_	_	0

- (1) DB0: Monitors block synchronization status.
 - 0: block out-of-synchronization
 - 1: block synchronized
- (2) DB4-DB7: Monitors the number of block synchronization forward protection steps. While a block is synchronized, if a BIC is not detected in a number of successive attempts, the number of attempts is decremented from the set number of block synchronization forward protection steps; when all the values of DB4 to DB7 change from 1 to 0, it is judged that the block is out of synchronization.

DB7	DB6	DB5	DB4	Remaining Number of Block Synchronization Forward Protection Steps		
0	0	0	0	0	1	Out of synchronization
0	0	0	1	1	Synchronization	•
!	1	1			detection	When BIC cannot be detected
1	1	1	1	15	>	Load during synchronization

5.4.5 Block Synchronization Set

This register forcibly sets block synchronization, and is used for testing.

Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
014H	Write	value	Х	х	х	Х	Х	х	Х	Х

x : don't care

5.4.6 Block Synchronization Clear

This register forcibly sets block out-of-synchronization. This setting is effective when a channel is changed, in clearing a previous synchronizing status, to permit faster synchronization for the new channel.

Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
015H	Write	value	Х	х	х	Х	Х	Х	Х	Х

x : don't care

5.4.7 Bit Number Monitor

These registers monitor bit numbers. They are used for testing. DB0 of the 017H register is MSB, and DB0 of the 016H register is LSB. Numbers 0 to 287 are displayed.

Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
016H	Read	value	0	0	0	0	0	0	0	0
			b7	b6	b5	b4	b3	b2	b1	b0

Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
017H	Read	value	_	_	_	_		_	_	0

b8

5.5 FRAME SYNCHRONIZATION REGISTERS

5.5.1 Number of Frame Synchronization Backward Protection Steps

This register specifies the number of times that synchronization points required for frame synchronization have to be detected in succession in order for the frame to be judged as being synchronized. When the block number changing points (= frame synchronization points: $272 \rightarrow 1$, $13 \rightarrow 14$, $136 \rightarrow 137$, and $149 \rightarrow 150$, under format B) are detected the same number of times as the specified number of successive steps (number of frame synchronization backward protection steps), frame synchronization is entered and the internal frame counter is synchronized with the detected block number.

									/ (')
Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
018H	Write	value	_	_	_	_	_	_	0	1

(1) DB0-DB1: Number of frame synchronization backward protection steps

DB1	DB0	Number of Frame Synchronization Backward Protection Steps
0	0	1
0	1	2
1	0	3
1	1	4

5.5.2 Number of Frame Synchronization Forward Protection Steps

This register specifies the number of times that successive unsuccessful attempts to detect the synchronization points required for frame synchronization that will cause a judgment that a frame is out of synchronization.

After frame synchronization, if the block number changing points (= frame synchronization points: $272 \rightarrow 1$, $13 \rightarrow 14$, $136 \rightarrow 137$, and $149 \rightarrow 150$, under format B) are not detected the same number of times as the specified number of successive steps (number of frame synchronization forward protection steps), the frame will be out of synchronization to terminate data reception. This register is used for initial settings.

(1)

								(1) —	
Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
019H	Write	value	_	_	_	_	0	1	0	0

(1) DB0-DB3: Number of frame synchronization forward protection steps

DB3	DB2	DB1	DB0	Number of Frame Synchronization Forward Protection Steps
0	0	0	0	0 (Inhibit)
0	0	0	1	1
:	:	:		
1	1	1	1	15

5.5.3 Frame Synchronization Monitor

- (1) Frame synchronization monitoring register (DB1)
- (2) Register for monitoring the number of frame synchronization forward protection steps (DB4-DB7)

Both (1) and (2) are for testing.

			(2)				<u>/</u> (1) <u> </u>			
Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
01AH	Read	value	0	0	0	0	_		0	_

- (1) DB1: Monitors frame synchronization status.
 - 0: frame out-of-synchronization
 - 1: frame synchronized
- (2) DB4-DB7: Monitors the number of frame synchronization forward protection steps. While a frame is synchronized, when successive attempts to detect frame synchronization points fail, that number of attempts is decremented from the set number of frame synchronization forward protection steps; when all the values of DB4 to DB7 change from 1 to 0, the frame is judged to be out of synchronization.

DB7	DB6	DB5	DB4	Remaining Number of Frame Synchronization Forward Protection Steps		
0	0	0	0	0	1	Out of synchronization
0	0	0	1	1	Synchronization detection	•
!		1	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1		uetection	When a frame synchronization point cannot be detected
1	1	1	1	15	>	Load when a synchronization
					ı	point is detected

5.5.4 Frame Synchronization Set

This register forcibly sets frame synchronization and is used for testing.

Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
01BH	Write	value	Х	х	х	Х	Х	Х	Х	Х

x : don't care

5.5.5 Frame Synchronization Clear

This register forcibly sets frame out-of-synchronization. This function is effective when a channel is changed, in clearing a previous synchronizing status, to permit faster synchronization for the new channel.

Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
01CH	Write	value	х	Х	Х	Х	Х	Х	Х	х

x : don't care

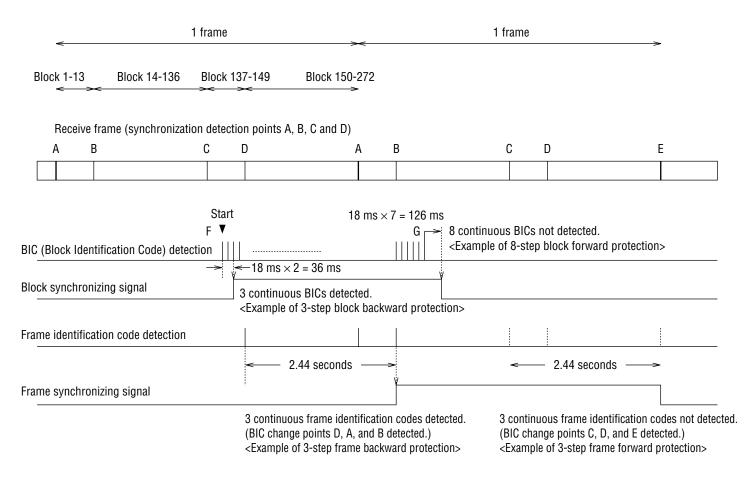
5.5.6 Block Number Monitor

These registers monitor block numbers and are used for testing. DB0 of 01EH register is MSB, and DB0 of 01DH register is LSB. Numbers 0 to 271 are displayed.

Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
01DH	Read	value	0	0	0	0	0	0	0	0
			b7	b6	b5	b4	b3	b2	b1	b0

Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
01EH	Read	value		_	_	_	_		_	0

b8



The frame synchronization time can become a maximum depending on the detection position; for example, the time between BCs, 2.21 seconds, is added to make it 4.65 seconds (the same is true for out-of-synchronization).

(Note) This figure is an example under frame format B.

Figure 5.5.1 Block and Frame Synchronization

5.5.7 Frame Format Specification

Address	Read/Write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
01FH	Write	value	_	_	_	_	_	_	1	0

B1	В0	Frame Format	Symbol	Note
0	0	Format A	A0	_
		Format A		Including
0	4		A1	realtime
0	ı		AI	information
				block.
1	0	Format B	В	Japan, FMSS
1	1	Format C	С	_

5.6 ERROR CORRECTION REGISTERS

5.6.1 Internal Memory Address Counter Clear

This command clears the address counter of internal memory (set to 0) before writing and reading an error correction data block. Since error correction is executed sequentially from address 0 of internal memory, the internal memory address counter must be cleared before writing. After error correction, it is necessary to clear the internal memory address counter to read data sequentially from address 0 of internal memory.

Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
020H	Write	value	Х	х	Х	Х	Х	Х	Х	X

x: don't care

5.6.2 Data Transfer Port for Error Correction

This port writes data before error correction and reads data after error correction.

When correcting an error in a horizontal (vertical) direction after clearing the internal memory address counter, write 34 (272) bytes of data to this port.

After correcting an error in a horizontal (vertical) direction, clear the internal memory address counter, then read 34 (272) bytes of data from this port.

When reading or writing data for this port, it is unnecessary to specify the horizontal (vertical) direction error correction mode.

Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
021H	Read/write	value	Undefined							
			b7	b6	b5	b4	b3	b2	b1	b0

5.6.3 Error Correction Start Signal

When start action specification data is written into DB0 to DB2, error correction starts in the specified mode. When error correction is completed, an interrupt is generated.

The operation status of the error correction circuit can be monitored by this register.

— (2) Read — (1) Write —

							/ (1) WIILC				
Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	
022H	Read/write	value	_	_	_	_	_	0	0	0	

(1) DB0 - DB2 (Write) : Error correction start mode specification

DB2	DB1	DB0	Start Action (write)
0	0	1	Horizontal error correction of receive block data (at address 003H
			on the 34-byte RAM) starts.
			Corrected data is written toaddress 003H on the RAM.
0	1	0	Vertical error correction of data written in address 021H on the
			272-byte RAM starts.
			Corrected data is written in address 021H on the RAM.
1	0	0	Horizontal error correction of data written in address 021H on the
			34-byte RAM starts.
			Corrected data is written in address 021H on the RAM.

(2) DB0 - DB2 (Read) : Monitor

The data written in this register can be used to monitor the error correction circuit operation status because the data is cleared after error correction is complete.

DB0: Displays the operation status of the horizontal error correction for receive block data.

DB1: Displays the operation status of the vertical error correction.

DB2: Displays the operation status of the 2nd horizontal error correction.

for each of these bits:

0: Error correction circuit is idle.

1: Error correction circuit is in operation.

5.6.4 CRC Result Indication

This register indicates a 14-bit CRC result. When horizontal direction error correction is executed, a 14-bit CRC is performed internally on corrected data and the result is indicated. This register is cleared immediately after error correction starts.

/4\

										<u>/_(1)</u>
Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
023H	Read	value	_	_	_	_	_	_	_	0

DB0: 14-bit CRC result

0: Normal1: Error

5.6.5 Error Correction Result Indication

This register indicates an error correction result.

If syndrome registers are all 0 after error correction, this register indicates a normal status. If not, it indicates an error. This register is cleared immediately after error correction starts.

In the case of a horizontal-direction correction, the result is indicated at DB7. In the case of a vertical-direction correction, the result is indicated at DB0-DB7 corresponding to bits 0-7.

			(2) ————————————————————————————————————									
Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0		
024H	Read	value	0	0	0	0	0	0	0	0		

(1) DB7: Horizontal-direction error correction result

0: Normal

1: Error

(2) DB0-DB7: Vertical direction error correction result (corresponding to bits 0-7)

0: Normal

1: Error

5.6.6 Majority Logic Threshold Value

This register sets the majority logic threshold value for error correction. The setup range is 1 to 17. This register is used for initial settings.

Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
025H	Write	value			_	0	1	0	0	0

DB4	DB3	DB2	DB1	DB0	Majority Logic Threshold Value
0	0	0	0	0	Inhibit
0	0	0	0	1	1
S	S	S	S	S	\$
0	1	0	0	0	8
S	S	S	S	S	\$
0	1	1	1	1	15
1	0	0	0	0	16
1	0	0	0	1	17

5.6.7 Internal Address Monitor

This register indicates the addresses (0-271) of internal memory for error correction. This is used for testing.

(1)												
Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0		
026H	Read	value	0	0	0	0	0	0	0	0		
			b7	b6	b5	b4	b3	b2	b1	b0		

										/
Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
027H	Read	value	_	_	_	_	_	_		0

b8

- Error correction involves external RAM, a microcontroller and MSM9552/9553.
- Transfer data in error correction units (horizontal direction equals 34 bytes, vertical direction equals 272 bytes) from external memory to the internal buffer of the MSM9552/9553. Error correction is then executed. Transfer data after error correction from the internal buffer to external memory.

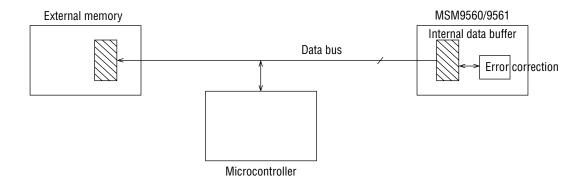
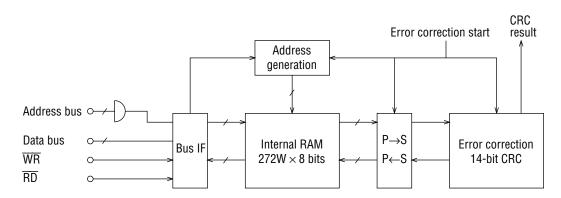


Figure 5.6.1 General Configuration of Error Correction



Note: CRC is executed on data after horizontal-direction error correction.

Figure 5.6.2 Configuration of Error Correction Section

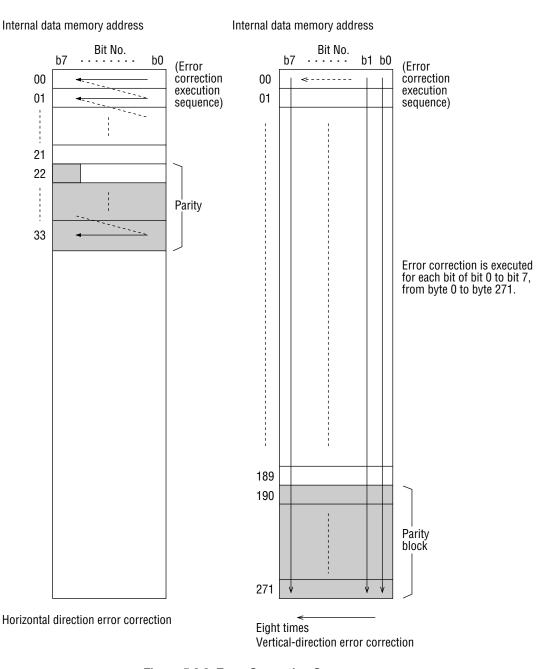


Figure 5.6.3 Error Correction Sequence

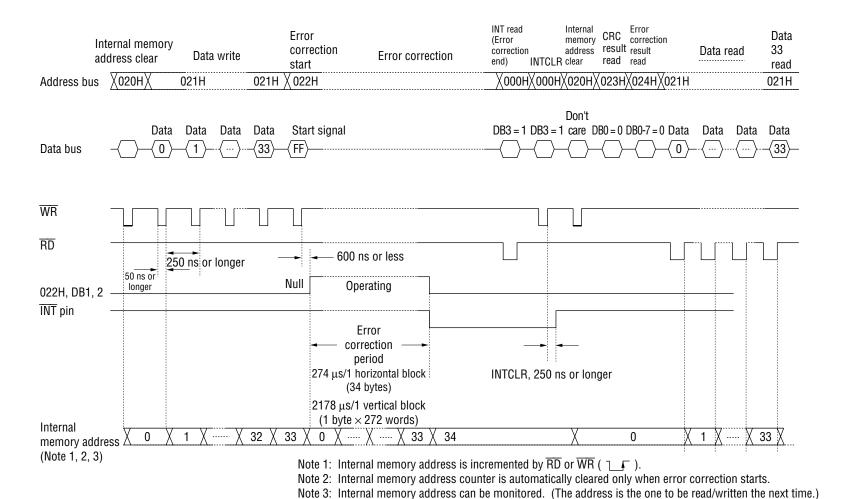


Figure 5.6.4 Error Correction Timing Diagram

5.7 LAYER 4 CRC REGISTERS

5.7.1 Layer 4 CRC Register Clear

This command clears the CRC register and sets all of its contents to 0 before layer 4 CRC processing. Execute this command once before reading the data group on which CRC processing is to be performed.

Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
028H	Write	value	Х	Х	Х	Х	Х	Х	Х	Х

x : don't care

5.7.2 Layer 4 CRC Data Buffer

Write the data group on which CRC processing is to be performed in byte units with a cycle of $4.5~\mu s$ or longer. The data written inside the IC is loaded to the CRC operation register and a shift operation is executed (eight times). The system then waits for the next data input.

Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
029H	Write	value	0	0	0	0	0	0	0	0

5.7.3 Layer 4 CRC Result Indication

This register indicates a layer 4 CRC result. After the last data of a data block is written, pause for at least $4.5~\mu s$ before reading.

										<u>/ (I) \</u>
Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
02AH	Read	value	_		_	_		_	_	0

(1) DB0: layer 4 CRC result

0: Normal1: Error

5.7.4 Layer 4 CRC Register

This register is used for writing initial values directly to the CRC operation register, and reading values which are still in progress.

With this function, layer 4 CRC processing for multiple data groups can be performed in parallel. For example, CRC processing for a short data group can be inserted while CRC processing for a long data group is in progress.

(1) Layer 4 CRC register high-order 8 bits

Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
02BH	Read/write	value	0	0	0	0	0	0	0	0
			b7	b6	b5	b4	b3	b2	b1	

(2) Layer 4 CRC register low-order 8 bits

Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
02CH	Read/write	value	0	0	0	0	0	0	0	0
			b15	b14	b13	b12	b11	b10	b9	b8

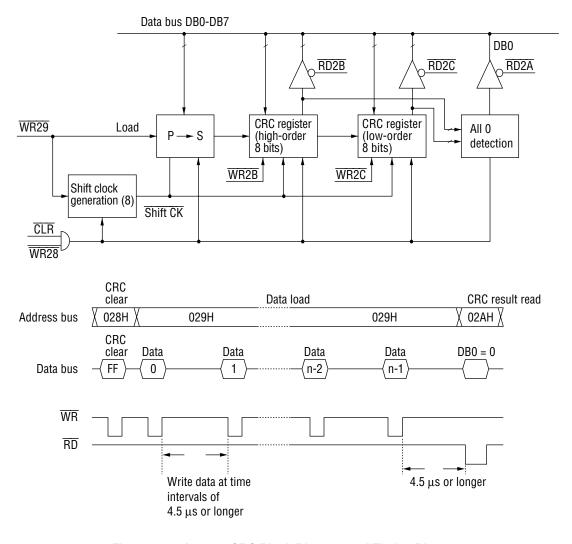


Figure 5.7.1 Layer 4 CRC Block Diagram and Timing Diagram

5.8 ANALOG SECTION CONTROL/MONITOR REGISTER

This register is used for level adjustment of the analog input signal (composite signal) and analog section test mode settings.

						— (J) —		/ (2) —	<u>/_(ı)</u>
Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
030H	Write	value	_		0	0	0	0	0	0

(1) DB0: DETC

Controls the input of analog input pin ADETIN.

- 0: Disables the input of analog input pin ADETIN, so that the input buffer amplifier is powered down (during FM multiplex broadcast reception).
- 1: Enables the input of analog input pin ADETIN, so that the input buffer amplifier is powered on.

The connections are switched as follows (available for input of a 16 kbps digital test signal):

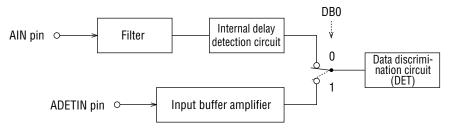


Figure 5.8.1 Switching Analog Input Pins

(2)DB1-DB2: SGAIN0, SGAIN1

This register is used for gain switching for the variable gain amplifier for analog input signal. These signals are used for initial settings.

Set the values of DB1 and DB2 so that the following expression is satisfied:

Peak value of the analog input signal (composite signal) \times gain = 1.5 to 2.0 V_{P-P} (MSM9552) $= 0.5 \text{ to } 0.9 \text{ V}_{P-P} \text{ (MSM9553)}$

This is effective for improving the S/N ratio.

SGAIN1	SGAIN0	Gain		
DB2	DB1	Gaili		
0	0	×1		
0	1	×1.5		
1	0	×2		
1	1	×3		

(3) DB3-DB5: M0-M2 Monitors internal filter output waveforms and controls MON pin (pin 1) output. Refer to Figure 5.8.2 for the part that can be monitored. After clear, the internal MON amplifier is powered OFF and the output becomes high impedance.

(M2) DB5	(M1) DB4	(M0) DB3	MON Pin (pin 1) Output
0	0	0	Internal monitor amplifier power off, high impedance output
0	0	1	LPF output of input stage
0	1	0	② BPF internal waveform 1
0	1	1	3 BPF internal waveform 2
1	0	0	④ BPF internal waveform 3
1	0	1	⑤ BPF output
1	1	0	Internal amplifier output
1	1	1	⑦ Delay detection output

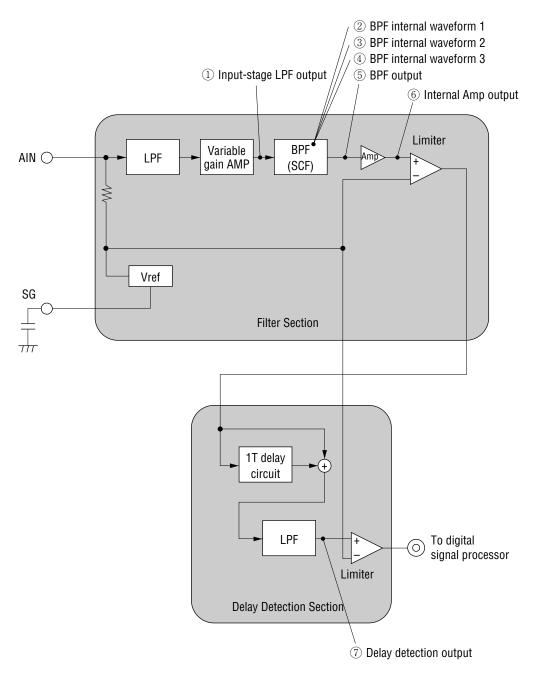


Figure 5.8.2 Analog Section Output Waveform Monitor

5.9 POWER DOWN CONTROL REGISTER

This is a power down setting register.

				/	<u> — (4) —</u>			<u>/</u> —(3) —	(2)	(1)
Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
031H	Write	Value	_	0	0	0	_	0	0	0

- (1) DB0: Analog section power down control
 - 0: Power down (operation stops).
 - 1: Power on (after power is turned on, several milliseconds are necessary until the circuit stabilizes).
- (2) DB1: Digital section power down control
 - 0: The digital section is power down, and the internal clock stops. Since the clock stops at "H", operation can be continued after power on.
 - 1: The digital section is power on. Operation starts from clock "H".
- (3) DB2: External oscillation control
 When input pin XOUTC = "1", operation of crystal oscillation circuits (XTAL1, XTAL2)
 is controlled as described below. The output pin XOUT is fixed to "L".
 - 0: Stops the operation of the crystal oscillation circuits.
 - 1: Starts the operation of the crystal oscillation circuits.

When input pin $\overline{\text{XOUTC}}$ = "0", the crystal oscillation circuits (XTAL1 and XTAL2) are always in an oscillation state, and the output pin XOUT always outputs oscillation clocks.

(4) Dividing of external clock (XOUT) The divided clocks to the XOUT pin are set up.

DB6 (XCK2)	DB5 (XCK1)	DB4 (XCK0)	Clock XOUT pin
0	0	0	8.192 MHz
0	0	1	4.096 MHz
0	1	0	2.048 MHz
0	1	1	1.024 MHz
1	0	0	0.512 MHz
1	0	1	0.256 MHz
1	1	0	0.128 MHz
1	1	1	0.064 MHz

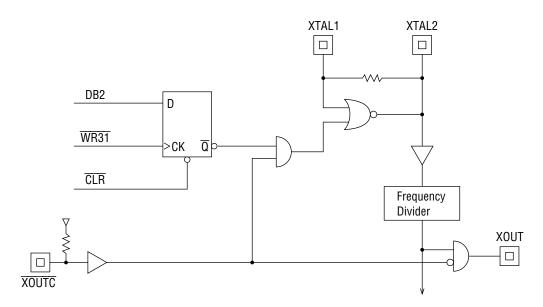


Figure 5.9.1 Oscillator Circuit Control

5.10 TEST CONTROL REGISTERS

5.10.1 Test Control 0

This register controls switching of the test pins (MOUT0-MOUT4).

				— (I) —						
Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
032H	Write	value	0	0	0	_	_	_	_	_

(1) DB5-DB7: See Table 5.10.1 for details.

5.10.2 Test Control 1

This register controls the decoding mode of serial receive data and test switching.

				/— (!	5) —	<u></u> _(1) _	<u></u> (4) –	(3)	(2)	(1)
Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
033H	Write	value	_	0	0	0	0	0	0	0

(1) DB0, DB4: Serial receive data output

Outputs serial receive data (serial receive data converted by the control in (3) to (5) below) to MOUT6 pin.

The output data changes at the rising edge of a 16 kHz regeneration data clock (MOUT5 pin).

DB4	DB0	MOUT 6 Pin Output				
0	0	Fixed to "L"				
0	1	Serial receive data after descrambling				
1	0	Carial reasing data before decorposibling				
1	1	erial receive data before descrambling				

(2) DB1: 16 kHz regeneration data clock

A 16 kHz regeneration data clock is output to the MOUT5 pin.

- 0: MOUT5 Pin is fixed to "L".
- 1: A 16 kHz regeneration data clock is output to the MOUT5 pin.
- (3) DB2: Differential decoding control
 - 0: Performs differential decoding to input data.
 - 1: Does not perform differential decoding. (In FM multiplex broadcast, differential decoding is not used, so use DB2 = "1".)
- (4) DB3: Descrambler (regeneration of dc component of data) control
 - 0: Descrambles input data other than BIC. (This is used for receiving FM multiplex broadcast.)
 - 1: Does not descramble. (This is used for testing.)

(5) DB5, DB6: Delay detector output control

DB6	DB5	Delay Detector Control (controls input data and data before 1T)	Purpose of Use
0	0	ENOR	FM multiplex broadcast reception
0	1	Through (data before 1T)	
1	0	EOD	For testing
1	1	EOR	

Table 5.10.1 Monitor Input/Output Pins

Test Control 0

Test Control				Addr	ess = 032H			
					(DB7,	DB6, DB5)		
			Extension Port	L	SI Internal Si	gnal Monito	(Note)	
Pin Pin Name No.	1/0		(110) (101)	TST0 (001)	TSTTI (010)	TSTB0 (011)	TSTB1 (100)	TSTC (111)
моито	8	Output	(000) 0FH register DB0	BPF limmiter output	TS11	FRCK0	FS	 /NC ^{*1}
MOUT1	9	Output	0FH register DB1	Delay detection output	TS21	FRCK1	BS	YNC *2
MOUT2	10	Output	0FH register DB2	DET output	TS10	FRCK2	RAMOUT	BICO *3
моитз	11	Output	0FH register DB3	SCF clock output	GATE	FRCK3	BICDET2	BIC1 *3
MOUT4	12	Output	0FH register DB4	Fixed to "L"	PHCK1	BCK	BICDET	BICDET1*4

Test Control 1

Pin Pin Name No.	Pin			Test control 1 Address = 033H					
	No. I/O	Test Co	ontrol 1	Test control 1 DB0, DB4					
			DB1		DB0	0	1	0	1
			0	1	DB4	0	0	1	1
MOUT5	13	Output	Fixed to "L"	CK16K		_			_
MOUT6	14	Output	_	_		Fixed to "L"	Serial receive data after descrambling	Serial red before des	

- (Note) Since the LSI internal signal monitor is normally used for LSI device shipment inspection, the user does not have to use it, but the items *1 to *4 below can be monitored.
 - *1 FSYNC → Frame synchronizing state "0": out of shnchronizing "1": synchronizing
 - *2 BSYNC → Block synchronizing state "0": out of shnchronizing
 - "1": synchronizing
 - *3 BICO, BIC1 \rightarrow BIC number indication

BIC0	0	1	0	1
BIC1	0	0	1	1
BIC No.	BIC1	BIC2	BIC3	BIC4

*4 BICDET1 \rightarrow BIC detection state

"0": detecting NG "1": detecting OK

5.11 I/O ADDRESS REGISTER

This register sets up an internal register address irrespective of pins A0 to A5. The address set up by this register becomes valid when IOEN (DB7) is set to "1". When \overline{CS} = "1" and \overline{IORD} = "0", data in the internal register is output onto the data bus. When \overline{CS} = "1" and \overline{IOWR} = "0", data on the data bus is written in the internal register.

		<u>(1)</u>					(2	2) ———		
Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
037H	Write	value	0	_	0	0	0	0	0	0

(1) DB7: IOEN

0: Address set up by this register is invalid.

1: Address set up by this register is valid as an internal address in the IC.

(2) DB0 - DB5:

Corresponds to external addresses A0 to A5.

5.12 EXTENDED PORT REGISTER

Data (B0 to B4) in this register is output to the monitor output pins MOUT0 to MOUT4 by writing 000xxxxx, 101xxxxx, or 110xxxxx to the port mode register (032H). Refer to the table 5.10.1.

Address	Read/write	Reset	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
00FH	Write	value	_	_	_	0	0	0	0	0

Usage example of the extended port

When the clock of the microcomputer that controls the MSM9552/9553 is supplied from the XOUT pin of the MSM9552/9553, the following two problems will occur:

1. When used with $\overline{XOUTC} = "1"$

When this register is cleared, the microcomputer does not operate, because the XOUT pin is fixed at "L".

2. When used with $\overline{XOUTC} = "0"$

When this register is cleared, oscillation does not stop even in the power down mode, because the XOUT pin always outputs clock.

The above troubles are cleared up using the extended port function.

By connecting the XOUTC pin and MOUT0 pin externally as shown below, XOUTC goes to "0" and XOUT pin outputs the clock, after clear.

By writing DB0 of 00FF to "1", XOUTC is set to "1", during power down mode.

As a result, oscillation does not stop during clear, and can be stopped by the software only during power down mode.

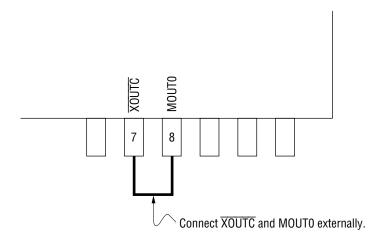
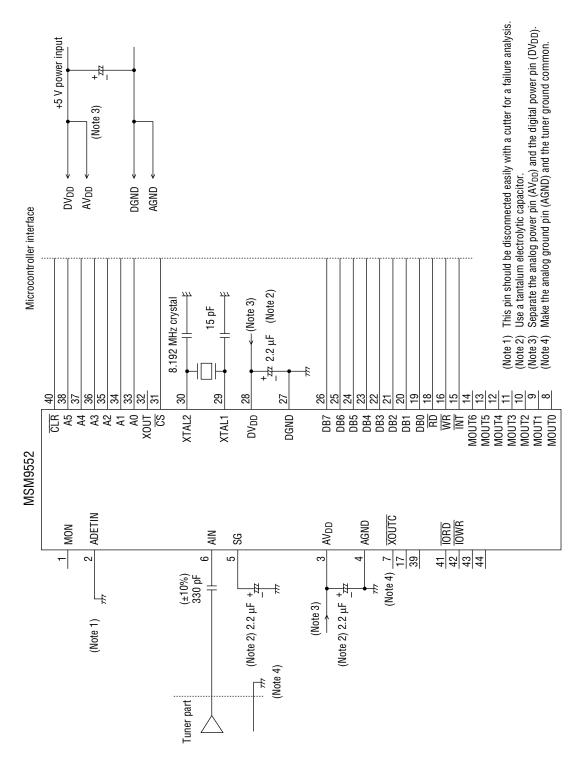


Figure 5.12.1 Usage Example of Extended Port

Chapter 6

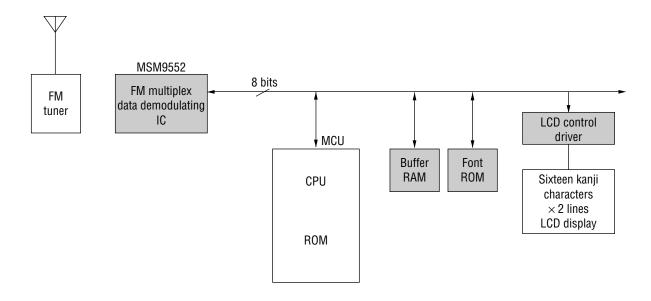
EXTERNAL CONNECTION EXAMPLE

6. EXTERNAL CONNECTION EXAMPLE



Chapter 7

APPLICATION CIRCUIT



APPENDIX

APPENDIX: INTERNATIONAL FRAME FORMAT (ITU-R Rec. BS1194)

1) Format A0: Frame according to method A, without insertion of real time blocks.

60 Blocks	BIC3	Information					
70 Blocks	BIC2	Information	CRC	Horizontal Parity			
60 Blocks	BIC1	Information					
82 Blocks	BIC4	Vertical Parity					

2) Format A1: Frame according to method A, with Static insertion of real time blocks.

60 Blocks	BIC3	Information							
70 Blocks	BIC2	Information	CRC	Horizontal Parity					
60 Blocks	BIC1	Information							
	BIC4	Vertica	Vertical Parity						
4x	BIC2	Real Time Information Block	CRC	Parity					
82 +12	BIC4	Vertica	I Parity						
Blocks 4x	BIC2	Real Time Information Block	CRC	Parity					
	BIC4	Vertica	I Parity						
4x	BIC2	Real Time Information Block	CRC	Parity					
	BIC4	Vertica	l Parity						

3) Format B: Frame according to method B, with block interleave.

····	BIC1	Information 1	CRC	Parity
13 Blocks	\$	\$	\$	\$
10 2100110	BIC1	Information 13	CRC	Parity
	BIC3	Information 14	CRC	Parity
	BIC3	Information 15	CRC	Parity
	BIC4	Parity 1		. ,
	BIC3	Information 16	CRC	Parity
	BIC3	Information 17	CRC	Parity
123 Blocks	BIC4	Parity 2		
	BIC3	Information 18	CRC	Parity
	\$	S	S	\$
	BIC4	Parity 40		
	BIC3	Information 95	CRC	Parity
	BIC3	Information 96	CRC	Parity
↓ [BIC4	Parity 41		
1	BIC2	Information 97	CRC	Parity
13 Blocks	\$	\$	S	\$
) [BIC2	Information 109	CRC	Parity
 	BIC3	Information 110	CRC	Parity
	BIC3	Information 111	CRC	Parity
	BIC4	Parity 42		
	BIC3	Information 112	CRC	Parity
	BIC3	Information 113	CRC	Parity
123 Blocks	BIC4	Parity 43		
	BIC3	Information 114	CRC	Parity
	S	S	S	\$
	BIC4	Parity 81		
	BIC3	Information 189	CRC	Parity
	BIC3	Information 190	CRC	Parity
) [BIC4	Parity 82		

4) Format C: Frame according to method C, block code only.

BIC3	Information	CRC	Parity	